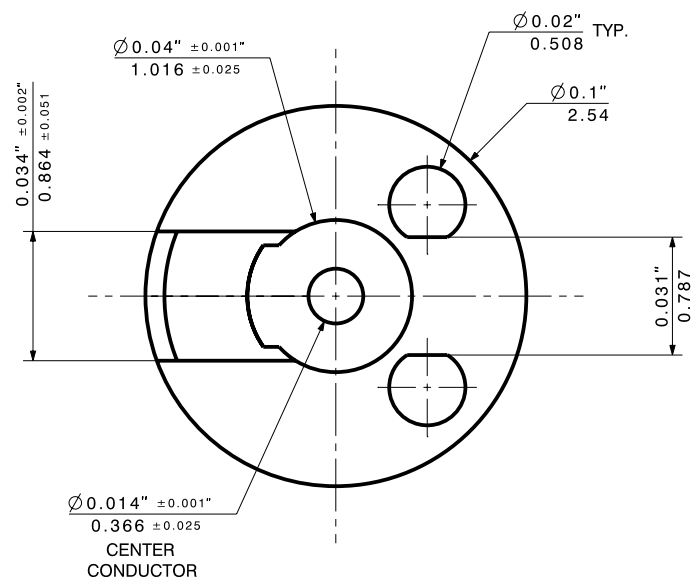
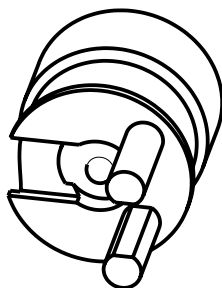
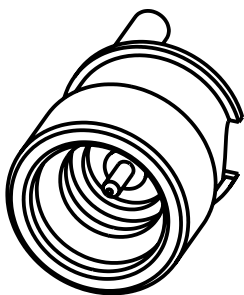
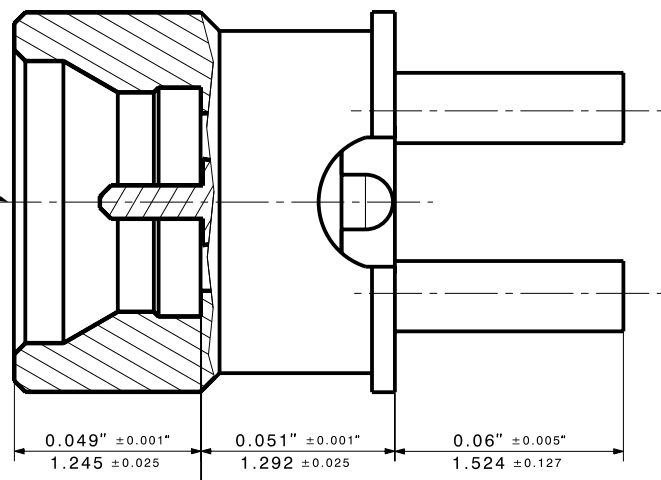


SMP3 Male
Full Detent



Component	Material	Material Std compliance	Finish		Finish Std compliance
Body	Beryllium Copper	ASTM B-196 UNS No. C17300 Temper TD04(H)	Gold Plate Nickel underplate	50 μ IN - 100 μ IN [1.27 μ M - 2.54 μ M]	Gold per ASTM B-488, Code C, Type II, Class 1.27
				50 μ IN - 100 μ IN [1.27 μ M - 2.54 μ M]	Nickel per SAE-AMS-QQ-N-290, Class I
Insulator	PTFE	ASTM D-1710	---	---	---
Contact	Beryllium Copper	ASTM B-196 UNS No. C17300 Temper TD04(H)	Gold Plate Nickel underplate	50 μ IN - 100 μ IN [1.27 μ M - 2.54 μ M]	Gold per ASTM B-488, Code C, Type II, Class 1.27
				50 μ IN - 100 μ IN [1.27 μ M - 2.54 μ M]	Nickel per SAE-AMS-QQ-N-290, Class I

Electrical Specification:
IMPEDANCE, 50.0 Ohms NOMINAL.
FREQUENCY, 65.0 GHz.

Mechanical:
Operating temperature range: -55° C to +165° C.

1 Interface definition, SMP3 male is designed and manufactured IAW MIL-STD-348 and will mate with SMP3 female connector designed and manufactured IAW MIL-STD-348.

2 Mounting Patterns, Customer specific factors including transmission line topology, substrate thickness and material, board-stackup, operating frequency, etc. must be submitted to HUBER+SUHNER Astrolab for analysis prior to release of final performance levels and mounting configuration.

Type: 81 SMP3-S50-0-FD2

All dimensions after treatment in millimeter (mm)

Assembly drawing

Released date:

alternative ID 29174S1-2-001 3D-ID PRO-01149826 A Sheet: 1/1

HUBER+SUHNER

SMP3 Male Surface Mount

Release
ID
DOU-01171244 A